IPC ASSOCIATION CONNEL ELECTRONICS INDUS	Material Compo © Copyright 2005. If international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information				
upplier Info	rmation														
Company name* Company				pany unique ID			Unique ID Authority					Response Date*			
nsemi											2023-06-08				
Contact Name			Title - Contact			Phone -	Phone - Contact*					Email - Contact*			
Product-Env-Ste	ewards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Repr	resentative*		Title - Representative			Phone -	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produc				roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number Mfr Ite		em Number Mfr Item Name			Effectiv	ve Date	Date Version Manufacturing Site		Manufacturing Site	1	Weight*	UOM	Unit Type	
		N24S64E	N24S64BC4DYT3G New OPN N24S64F EEPROM in thin C		4BC4DYT3G - 64KB I CSP package	2C 2023-0	6-08		CNQ		(0.3803	mg	Each	
Ianufacturir	ng Proccess Informat	ion													
Terminal Plating / Grid Array Material T			Ferminal Base Alloy J-STD-020 MSL		-STD-020 MSL Rating	Pe	Peak Process Body Temperature Max Time		e Max Time at Peak	Temperat	ure Numl	per of Reflow Cyc	les		
SnAgCu		C	CU Alloy 1			26	60 C		C	30	secon	ds 3			
omments															
vel 1 - maximu	m time at peak temperatu	re during sol	ldering is 10-3	30 seconds	·					·		·	·	·	
or more inform	ation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, on independently verified information provided by others, Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall a											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Backside Protection Film	0.0211	mg		Epoxy resin	proprietary data		0.0044	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0004	mg
			Supplier	Acrylic resins	Proprietary Data		0.0044	mg
			Supplier	Silica (SiO2)	14464-46-1		0.0119	mg
Die	0.271	mg	Supplier	Silicon (Si)	7440-21-3		0.271	mg
Protection coat	0.0169	mg		Polyimide	proprietary data		0.0169	mg
RDL	0.013	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0129	mg
Solder Ball	0.0448		Supplier	Silver (Ag)	7440-22-4		0.0018	mg
			Supplier	Tin (Sn)	7440-31-5		0.0428	mg
			Supplier	Copper (Cu)	7440-50-8		0.0002	mg
Under Bump Metal	0.0135	"	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0134	mg